

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wai-Yi Lien</td> <td>04/19/2004</td> </tr> <tr> <td>Chung-Long Chang</td> <td>04/19/2004</td> </tr> <tr> <td>Jhy-Chyurn Guo</td> <td>05/04/2004</td> </tr> <tr> <td>John Chern</td> <td>04/19/2004</td> </tr> </tbody> </table>		Name	Execution Date	Wai-Yi Lien	04/19/2004	Chung-Long Chang	04/19/2004	Jhy-Chyurn Guo	05/04/2004	John Chern	04/19/2004
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Wai-Yi Lien	04/19/2004										
Chung-Long Chang	04/19/2004										
Jhy-Chyurn Guo	05/04/2004										
John Chern	04/19/2004										
<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	Taiwan Semiconductor Manufacturing Company, Ltd.										
<b>Street Address:</b>	No. 8, Li-Hsin Rd. 6										
<b>Internal Address:</b>	Science-Based Industrial Park										
<b>City:</b>	Hsin-Chu										
<b>State/Country:</b>	TAIWAN										
<b>Postal Code:</b>	300-77										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10823874</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10823874						
Property Type	Number										
Application Number:	10823874										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(214)200-0853										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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Total Attachments: 3  
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**500005428**

**PATENT  
 REEL: 015034 FRAME: 0817**

**CH \$40.00 10823874**



**ASSIGNMENT**

WHEREAS, we,

- |     |                  |    |                          |
|-----|------------------|----|--------------------------|
| (1) | Wai-Yi Lien      | of | Hsin-Chu, Taiwan, R.O.C. |
| (2) | Chung-Long Chang | of | Hsin-Chu, Taiwan, R.O.C. |
| (3) | Jhy-Chyurn Guo   | of | Hsin-Chu, Taiwan, R.O.C. |
| (4) | John Chern       | of | Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

**A DEVICE AND METHOD FOR PROVIDING SHIELDING IN RADIO  
FREQUENCY INTEGRATED CIRCUITS TO REDUCE NOISE COUPLING**

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
  X   filed on April 14, 2004 and assigned application number 10/823,874; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Wai-Yi Lien

Residence Address:

(address) ✓

NO. 5, Alley 53, Lane 162, Gaotsuei Rd. 莊國威  
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Taiwan, R.O.C.

Dated: ✓

Apr. 19, 2004

✓ Wai-Yi Lien  
Inventor Signature

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Inventor Name: Chung-Long Chang

Residence Address:

(address) ✓

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Taiwan, R.O.C.

Dated: ✓

April, 19 2004

✓ Chung-Long Chang  
Inventor Signature

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Inventor Name: Jhy-Chyurn Guo

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(address) ✓

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Taiwan, R.O.C.

Dated: ✓

May 04, 2004

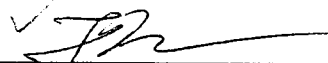
✓ Jhy-Chyurn Guo  
Inventor Signature

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Inventor Name: John Chern

Residence Address: (address) 3 MIN HSIANG 1ST ST.,  
Hsin-Chu, Taiwan 300, R.O.C.  
Taiwan, R.O.C.

Dated: ✓ 04/19/2004

✓   
Inventor Signature

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R-72205.1